

Description

The VSM20P05Y uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = -20V, I_D = -5A$

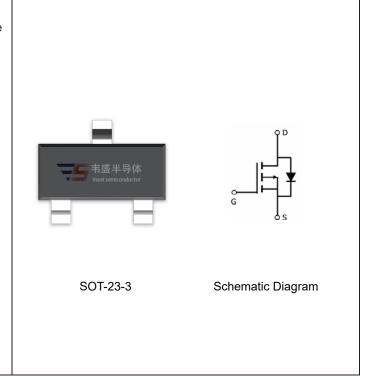
 $R_{DS(ON)}$ < 25m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < $40m\Omega$ @ V_{GS} =-2.5V

- High power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Motor drive
- Load switch
- Power management



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM20P05Y-S2	VSM20P05Y	SOT-23-3	Ø180mm	8mm	3000 units

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	I _D	-5	А
Drain Current-Pulsed (Note 1)	I _{DM}	-20	А
Maximum Power Dissipation	P _D	1.5	W
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	83.3	°C/W

Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-20	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V	-	-	-1	μA	



Cata Pady Lackaga Current	1	V _{GS} =±12V,V _{DS} =0V			±100	nA		
Gate-Body Leakage Current	I _{GSS}	V _{GS} -±12V,V _{DS} -UV	_	_	±100	IIA		
On Characteristics (Note 3)								
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-0.5	-0.7	-1.4	V		
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-5A	-	20	25	mΩ		
Diani-Source On-State Resistance		V_{GS} =-2.5V, I_D =-5A		30	40	mΩ		
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-5A	-	17	-	S		
Dynamic Characteristics (Note4)								
Input Capacitance	C _{lss}	\/ - 40\/\/ -0\/	-	620	-	PF		
Output Capacitance	Coss	V_{DS} =-10V, V_{GS} =0V, F=1.0MHz	-	125	-	PF		
Reverse Transfer Capacitance	C _{rss}	F-1.UIVITZ	-	64	-	PF		
Switching Characteristics (Note 4)				•	•			
Turn-on Delay Time	t _{d(on)}		-	4.5	-	nS		
Turn-on Rise Time	t _r	V_{DD} =-10V, R_L =10 Ω ,	-	9.2	-	nS		
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5 V , R_{GEN} =6 Ω	-	18.7	-	nS		
Turn-Off Fall Time	t _f		-	3.3	-	nS		
Total Gate Charge	Q_g		-	15	-	nC		
Gate-Source Charge	Q _{gs}	V _{DS} =-10V,I _D =-5A,V _{GS} =-4.5V	-	1.8	-	nC		
Gate-Drain Charge	Q_{gd}		-	2.8	-	nC		
Drain-Source Diode Characteristics								
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-5A	-	-	-1.2	V		

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- **4.** Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

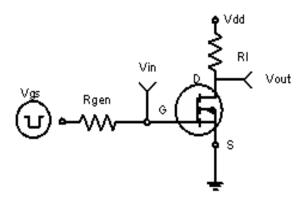


Figure 1 Switching Test Circuit

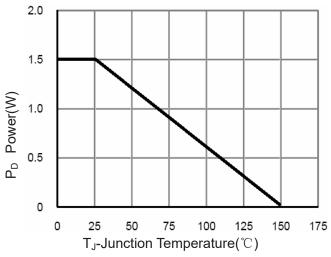


Figure 3 Power Dissipation

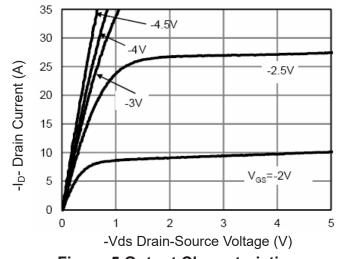


Figure 5 Output Characteristics

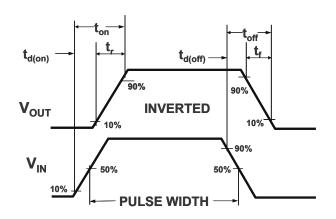


Figure 2 Switching Waveforms

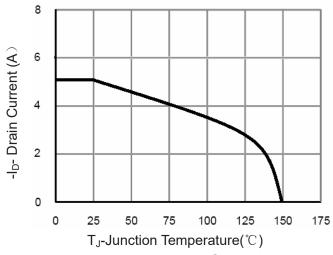


Figure 4 Drain Current

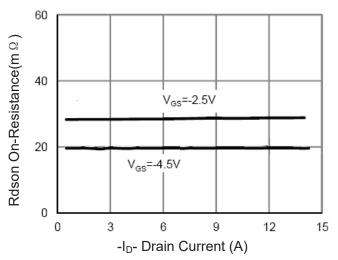


Figure 6 Drain-Source On-Resistance



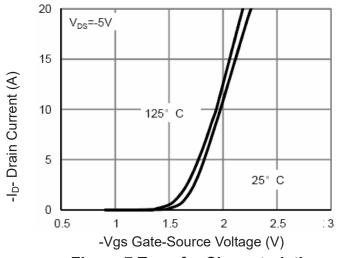


Figure 7 Transfer Characteristics

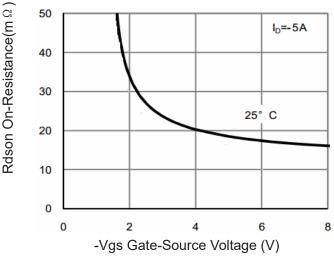
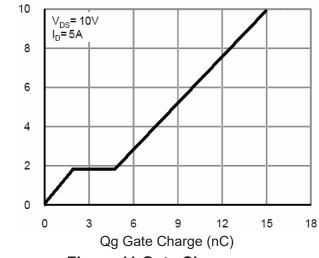


Figure 9 Rdson vs Vgs



-Vgs Gate-Source Voltage (V)

Figure 11 Gate Charge

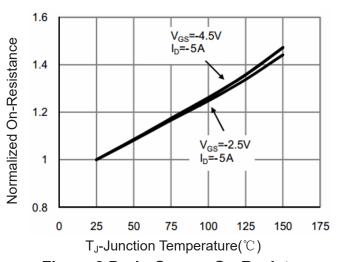


Figure 8 Drain-Source On-Resistance

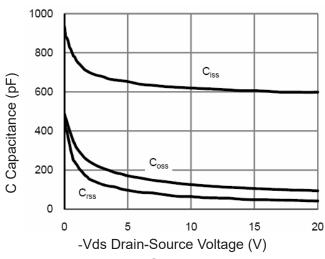


Figure 10 Capacitance vs Vds

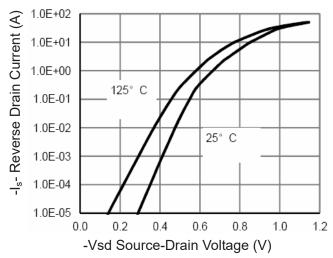


Figure 12 Source- Drain Diode Forward



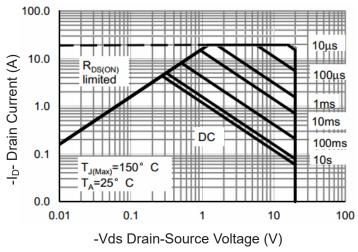


Figure 13 Safe Operation Area

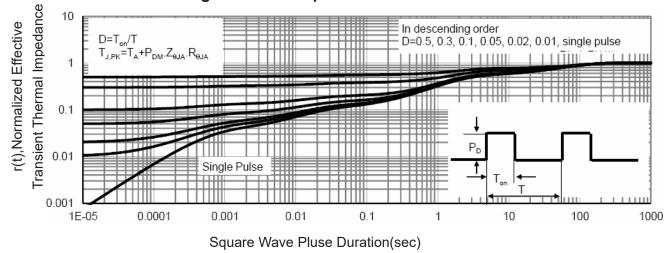


Figure 14 Normalized Maximum Transient Thermal Impedance